



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2012-12-11
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	------	----------------------------	----------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L6598D013TR	KMQ7*U370BDZ	A	SH1A	2012-12-11
Amount		UoM	Unit type	ST ECOPACK Grade
153.60		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	9.9 - 3.9 - 1.52	16	gull wing	
Comment	SO 16 .15 TO JEDEC MS-012			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KMQ7*U3708DZ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	4.924	mg	supplier	die	Silicon (Si)	7440-21-3		4.816	mg	978067	31354
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	1422	46
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.031	mg	6296	202
die (s)				supplier	passivation	Silicon Oxide (SiO2)	7631-86-9		0.043	mg	8733	280
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.003	mg	609	20
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.024	mg	4874	156
Leadframe	Copper & its alloys	24.148	mg	supplier	alloy	Copper (Cu)	7440-50-8		23.493	mg	972876	152949
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.553	mg	22900	3600
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.033	mg	1367	215
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.029	mg	1201	189
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.037	mg	1532	241
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	41	7
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	41	7
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	41	7
Die attach	Other inorganic materials	0.9	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.45	mg	500000	2930
Die attach				supplier	glue or tape	Aluminium (Al)	7429-90-5		0.315	mg	350000	2051
Die attach				supplier	glue or tape	acrylic resin	Proprietary		0.045	mg	50000	293
Die attach				supplier	glue or tape	Ethylene glycol dicyclopentyl ether acrylate	65983-31-5		0.072	mg	80000	469
Die attach				supplier	glue or tape	[3-(2,3-epoxypropoxy)propyl] trimethoxysilan	2530-83-8		0.009	mg	10000	59
Die attach				supplier	glue or tape	Butadiene copolymer	68891-50-9		0.009	mg	10000	59
Bonding wire	Other inorganic materials	0.133	mg	supplier	wire	Copper (Cu)	7440-50-8		0.133	mg	1000000	866
encapsulation	Other inorganic materials	123.495	mg	supplier	mold compound	Silica, vitreous	60676-86-0		108.306	mg	877007	705117
encapsulation				supplier	mold compound	Epoxy resin A	EC 413-900-7		4.939	mg	39994	32155
encapsulation				supplier	mold compound	Epoxy resin B	29690-82-2		4.939	mg	39994	32155
encapsulation				supplier	mold compound	phenol resin	Proprietary		3.705	mg	30001	24121
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.371	mg	3004	2415
encapsulation				supplier	mold compound	additive	Proprietary		1.235	mg	10000	8040